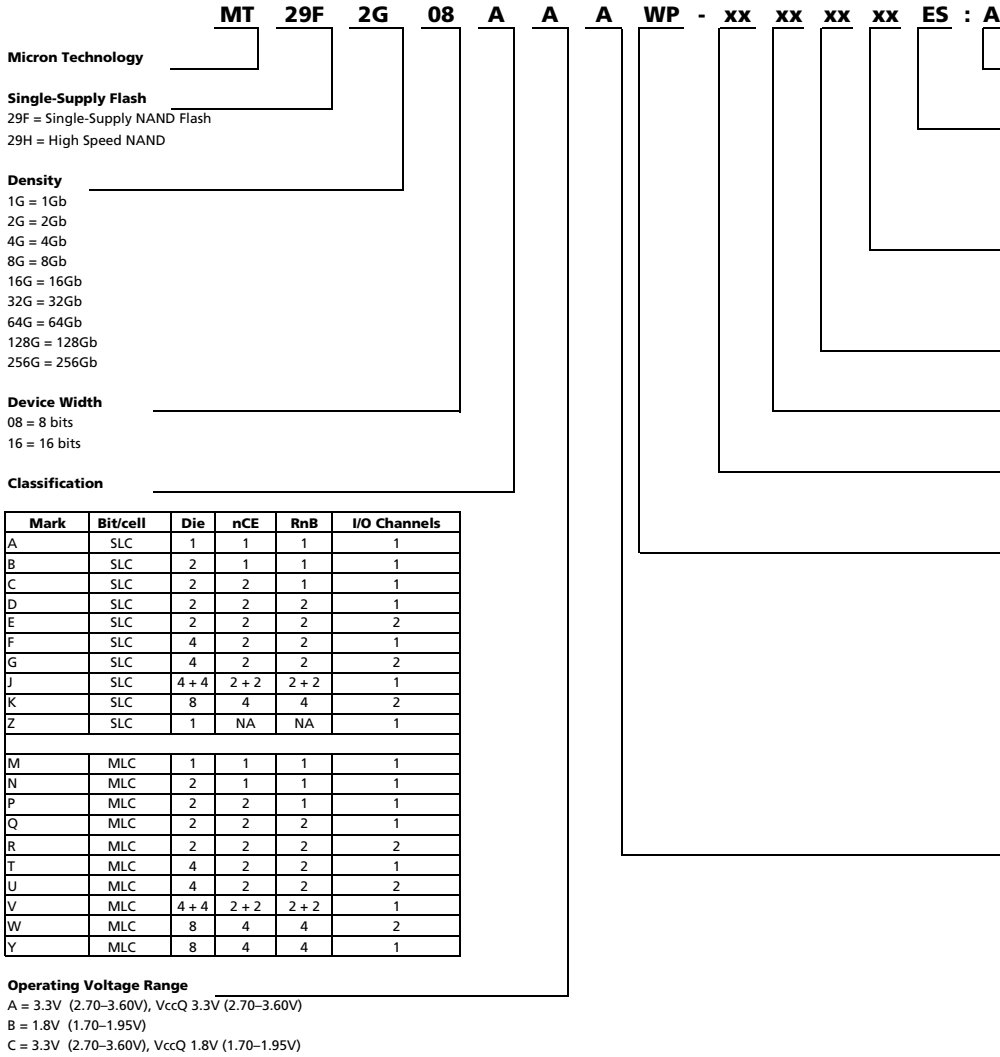


Standard NAND Flash Part Numbering System

Micron's part numbering system is available at www.micron.com/support/designsupport/documents/png

Standard NAND Flash*



Design Revision (shrink)

A = 1st design revision

Production Status

Blank = Production
ES = Engineering samples
QS = Qualification samples
MS = Mechanical samples

Operating Temperature Range

Blank = Commercial (0°C to +70°C)
ET = Extended (-40°C to +85°C)
WT = Wireless (-25°C to +85°C)

Block Option (Reserved for use)

Blank = Standard device

Flash Performance

Blank = Full specification

Speed Grade (MT29H Only)

15 = 133 MT/s
12 = 166 MT/s

Package Code

WP = 48-pin TSOP I (CPL version) (Pb-free)
WC = 48-pin TSOP I (OCPL version) (Pb-free)
H1 = 100-ball VFBGA (Pb-free), 12 x 18 x 1.0
H2 = 100-ball TFBGA (Pb-free), 12 x 18 x 1.2
HC = 63-ball VFBGA, 10.5 x 13 x 1.0
C2 = 52-pad ULGA, 12 x 17 x 0.4 (use TBD)
C3 = 52-pad ULGA, 12 x 17 x 0.65
C4 = 52-pad VLGA, 12 x 17 x 1.0 (SDP/DDP/QDP)
C5 = 52-pad VLGA, 14 x 18 x 1.0 (SDP/DDP/QDP)
C6 = 52-pad LLGA, 14 x 18 x 1.47 (8DP, QDP, DDP)
C7 = 48-pad LLGA, 12 x 20 x 1.47 (8DP)
SWC = 48-pin Stacked TSOP (OCPL version) (Pb-free)
SWP = 48-pin Stacked TSOP (CPL version) (Pb-free)

Generation (M29 only)/Feature Set

A = 1st set of device features
B = 2nd set of device features (rev only if different than 1st set)
C = 3rd set of device features (rev only if different)
D = 4th set of device features (rev only if different)
etc.

*Contact Micron for help differentiating between standard and next-generation NAND offerings.

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